Jue Wang

List of Publications by Year in descending order

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		1684188	2053705	
9	77	5	5	
papers	citations	h-index	g-index	
9 all docs	9 docs citations	9 times ranked	102 citing authors	

#	Article	IF	Citations
1	Sidewall-Implanted Trench Termination for 4H-SiC Devices With High Breakdown Voltage and Low Leakage Current. IEEE Electron Device Letters, 2022, 43, 104-107.	3.9	6
2	Investigation of SiC Trench MOSFETs' Reliability under Short-Circuit Conditions. Materials, 2022, 15, 598.	2.9	0
3	Degradation of 4H-SiC Trench MOSFET under single and repetitive short-circuit stress. , 2021, , .		O
4	A Novel SiC LDMOS with Electric Field Optimization by Step Doping Technology. , 2020, , .		2
5	Design and Characterization of Area-Efficient Trench Termination for 4H-SiC Devices. IEEE Journal of Emerging and Selected Topics in Power Electronics, 2019, 7, 1519-1526.	5 . 4	6
6	Investigation of 1200 V SiC MOSFETs' Surge Reliability. Micromachines, 2019, 10, 485.	2.9	22
7	Correction to "Trench Termination With SiO2-Encapsulated Dielectric for Near-Ideal Breakdown Voltage in 4H-SiC Devices―[Dec 18 1900-1903]. IEEE Electron Device Letters, 2019, 40, 353-353.	3.9	O
8	Experimental Demonstration and Analysis of a 1.35-kV 0.92-m \$Omega cdot ext {cm}^{2}\$ SiC Superjunction Schottky Diode. IEEE Transactions on Electron Devices, 2018, 65, 1458-1465.	3.0	25
9	Trench Termination With SiO ₂ -Encapsulated Dielectric for Near-Ideal Breakdown Voltage in 4H-SiC Devices. IEEE Electron Device Letters, 2018, 39, 1900-1903.	3.9	16